TOSHIBA RECTIFIER SILICON DIFFUSED JUNCTION TYPE

U1BC44,U1GC44,U1JC44

FOR HYBRID USE

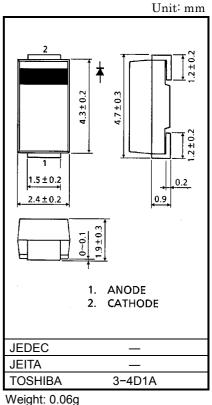
• Average Forward Current $I_{F(AV)} = 1.0A$

• Repetitive Peak Reverse Voltage $V_{RRM} = 100, 400, 600V$

Mini Plastic Mold Package

MAXIMUM RATINGS (Ta = 25°C)

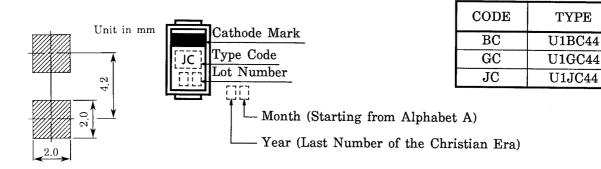
CHAF	RACTERIST	IC	SYMBOL	RATING	UNIT	
		U1BC44		100		
Repetitive Peak Reverse Voltage		U1GC44	V_{RRM}	400	V	
		U1JC44		600		
Average Forward	On Ceram	ic Substrate	l=	1.0 (Ta = 75°C)	А	
Current	On Glass- Substrate	ероху	^I F (AV)	0.9 (Ta = 25°C)		
Peak One Cycl	e Surge For	ward	l	30 (50Hz)	Α	
Current (Non-F	Repetitive)		IFSM	33 (60Hz)	A	
Junction Tempo	erature		Tj	-40~150	°C	
Storage Tempe	erature Ranç	ge	T _{stg}	-40~150	°C	

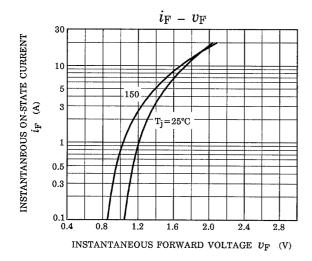


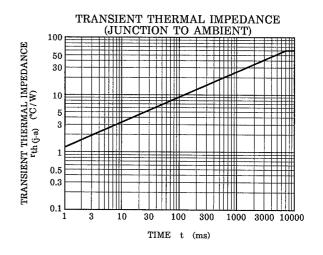
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL		TEST CONDITION	MIN	TYP.	MAX	UNIT
Peak Forward Voltage	V_{FM}	I _{FM} = 1.0A		_	_	1.2	V
Repetitive Peak Reverse Current		V _{RRM}	= Rated	_	_	10	μΑ
Thermal Resistance	R _{th (j-a)}	DC	On ceramic substrate	_	_	60	°C/W
Thermal Nesislance			On glass-epoxy substrate	_	_	120	C / VV

STANDARD SOLDERING PAD

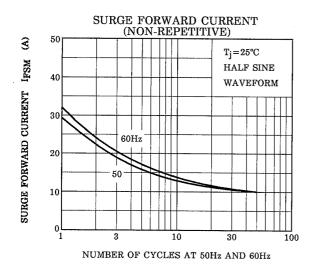






160											
					CER SSTR	AMI ATE	c _				
120				_							
80]	ASS-E		XY.					/		
40											
0		 0.2	0.	.4	0	.6	0.	8	1.	0	

			ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
	Soldering land	: a□	$2 \mathrm{mm}^\square$	6mm [□]
	Substrate size	: b□	$50 \mathrm{mm}^\square$	50mm [□]
	Substrate thickness	: c□	0.64t	1.6t
A)			a	c



2

RESTRICTIONS ON PRODUCT USE

Handbook" etc..

000707EAA

- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
 In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk.
- The information contained herein is presented only as a guide for the applications of our products. No
 responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other
 rights of the third parties which may result from its use. No license is granted by implication or otherwise under
 any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.